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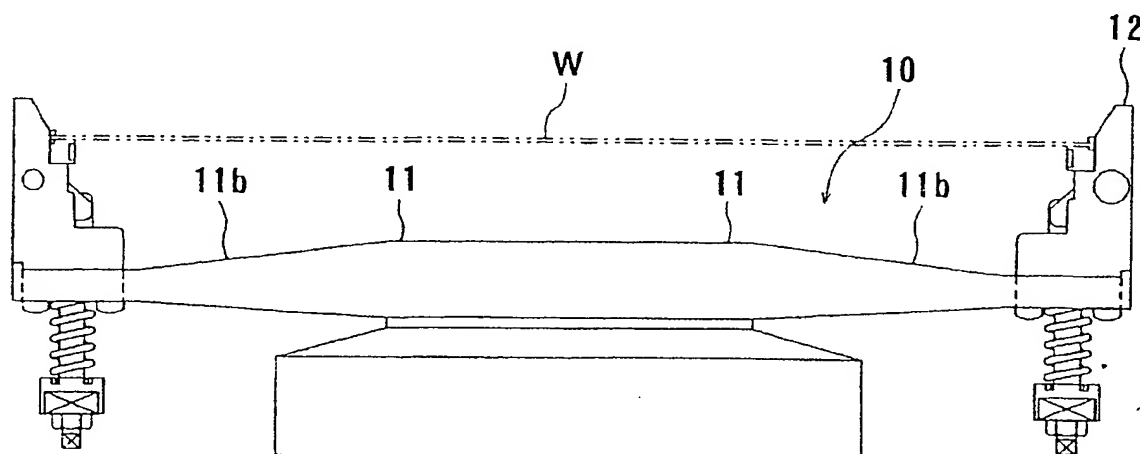
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(54) Title: SUBSTRATE CLEANING APPARATUS AND METHOD



(57) Abstract: A substrate cleaning apparatus is used for cleaning and drying a substrate such as a semiconductor wafer used in a semiconductor fabricating process or the like. The substrate cleaning apparatus includes a substrate holding mechanism (10) configured to hold the substrate (W), and a rotating mechanism (20) configured to rotate the substrate holding mechanism (10). At least one of components of the substrate cleaning apparatus has a surface structure to which droplets are hardly attached.